



High-end Power Semiconductor Manufacturer

KP300A 2000V-2800V

Phase Control Thyristor

- High power cycling capability
- Low on-state and switching losses
- Designed for traction and industrial applications



Mean on-state current	I_{TAV}	300 A			
Repetitive peak off-state voltage	V_{DRM}	2000 – 2800 V			
Repetitive peak reverse voltage	V_{RRM}				
Turn-off time	t_q	200 μ s			
V_{DRM} , V_{RRM} , V	2000	2200	2400	2600	2800
Voltage code	20	22	24	26	28
T_j , $^{\circ}$ C			-60 – 125		

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I_{TAV}	Mean on-state current	A	300	$T_c=85^{\circ}\text{C}$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TRMS}	RMS on-state current	A	471	$T_c=85^{\circ}\text{C}$, Double side cooled 180° half-sine wave; 50 Hz	
I_{TSM}	Surge on-state current	kA	6.5	$T_j=T_{j\max}$	180° half-sine wave; 50 Hz ($t_p=10$ ms); single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=2$ A; $t_{GP}=50 \mu\text{s}$; $di_G/dt \geq 1 \text{ A}/\mu\text{s}$
			7.5	$T_j=25^{\circ}\text{C}$	
I^2t	Safety factor	$\text{A}^2\cdot 10^3$	6.8	$T_j=T_{j\max}$	180° half-sine wave; 60 Hz ($t_p=8.3$ ms); single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=2$ A; $t_{GP}=50 \mu\text{s}$; $di_G/dt \geq 1 \text{ A}/\mu\text{s}$
			7.8	$T_j=25^{\circ}\text{C}$	
			211	$T_j=T_{j\max}$	180° half-sine wave; 50 Hz ($t_p=10$ ms); single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=2$ A; $t_{GP}=50 \mu\text{s}$; $di_G/dt \geq 1 \text{ A}/\mu\text{s}$
			279	$T_j=25^{\circ}\text{C}$	
			193	$T_j=T_{j\max}$	180° half-sine wave; 60 Hz ($t_p=8.3$ ms); single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=2$ A; $t_{GP}=50 \mu\text{s}$; $di_G/dt \geq 1 \text{ A}/\mu\text{s}$
			256	$T_j=25^{\circ}\text{C}$	
BLOCKING					
V_{DRM} , V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	2000–2800	$T_{j\min} < T_j < T_{j\max}$ 180° half-sine wave; 50 Hz; Gate open	
V_{DSM} , V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	2100–2900	$T_{j\min} < T_j < T_{j\max}$ 180° half-sine wave; 50 Hz; single pulse; Gate open	
V_D , V_R	Direct off-state and Direct reverse voltages	V	0.75 V_{DRM} 0.75 V_{RRM}	$T_j=T_{j\max}$ Gate open	

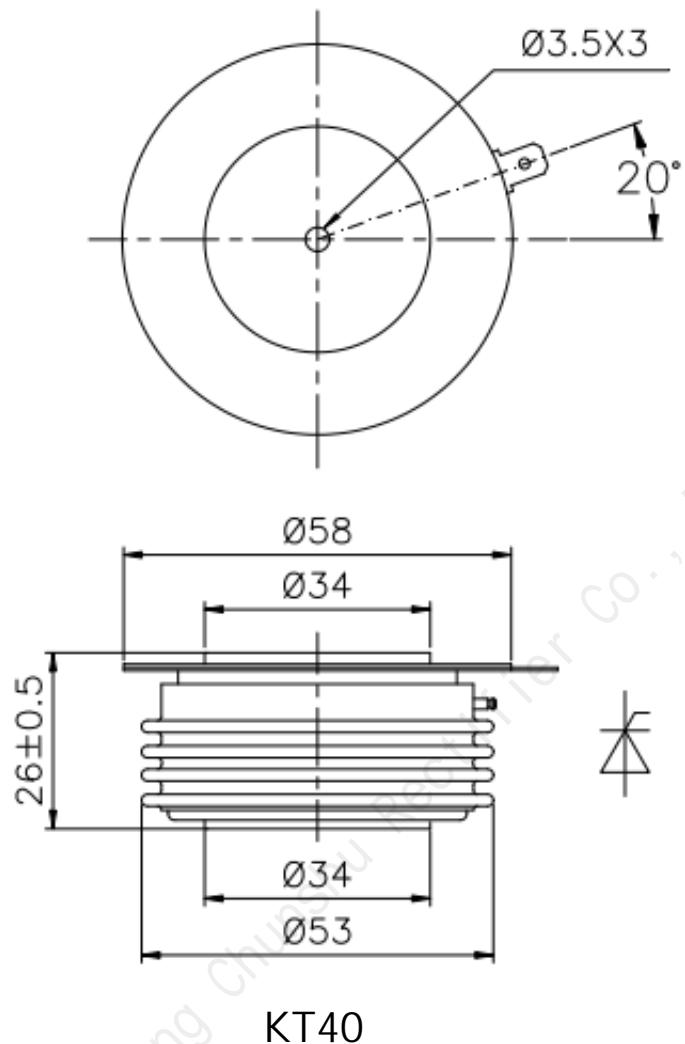
TRIGGERING				
I_{FGM}	Peak forward gate current	A	6	$T_j=T_{j \max}$
V_{RGM}	Peak reverse gate voltage	V	5	
P_G	Gate power dissipation	W	3	$T_j=T_{j \max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1$ Hz)	A/ μ s	320	$T_j=T_{j \max}; V_D=0.67V_{DRM}; I_{TM}=2 I_{TAV};$ Gate pulse: $I_G=2$ A; $t_{GP}=50$ μ s; $di_G/dt \geq 1$ A/ μ s
THERMAL				
T_{stg}	Storage temperature	°C	-60 – 125	
T_j	Operating junction temperature	°C	-60 – 125	
MECHANICAL				
F	Mounting force	kN	9.0 – 11.0	
a	Acceleration	m/s ²	50 100	Device unclamped Device clamped

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions		
ON-STATE						
V_{TM}	Peak on-state voltage, max	V	2.20	$T_j=25$ °C; $I_{TM}=1005$ A		
$V_{T(TO)}$	On-state threshold voltage, max	V	1.20	$T_j=T_{j \max};$ $0.5 \pi I_{TAV} < I_T < 1.5 \pi I_{TAV}$		
r_T	On-state slope resistance, max	$m\Omega$	1.510			
I_L	Latching current, max	mA	700	$T_j=25$ °C; $V_D=12$ V; Gate pulse: $I_G=2$ A; $t_{GP}=50$ μ s; $di_G/dt \geq 1$ A/ μ s		
I_H	Holding current, max	mA	300	$T_j=25$ °C; $V_D=12$ V; Gate open		
BLOCKING						
I_{DRM}, I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	70	$T_j=T_{j \max};$ $V_D=V_{DRM}; V_R=V_{RRM}$		
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage ¹⁾ , min	V/ μ s	1000	$T_j=T_{j \max};$ $V_D=0.67V_{DRM};$ Gate open		
TRIGGERING						
V_{GT}	Gate trigger direct voltage, max	V	2.50 2.00	$T_j=25$ °C $T_j=T_{j \max}$	$V_D=12$ V; $I_D=3$ A; Direct gate current	
I_{GT}	Gate trigger direct current, max	mA	250 200	$T_j=25$ °C $T_j=T_{j \max}$		
V_{GD}	Gate non-trigger direct voltage, min	V	0.25	$T_j=T_{j \max};$ $V_D=0.67V_{DRM};$		
I_{GD}	Gate non-trigger direct current, min	mA	10.00	Direct gate current		
SWITCHING						
t_{gd}	Delay time	μ s	2.50	$T_j=25$ °C; $V_D=0.4V_{DRM}; I_{TM}=I_{TAV};$ Gate pulse: $I_G=2$ A; $t_{GP}=50$ μ s; $di_G/dt \geq 1$ A/ μ s		
t_q	Turn-off time ²⁾ , max	μ s	200	$dv_D/dt=50$ V/ μ s; $T_j=T_{j \max}; I_{TM}=I_{TAV};$ $di_R/dt=-10$ A/ μ s; $V_R=100$ V; $V_D=0.67V_{DRM}$		

THERMAL					
R_{thjc}	Thermal resistance, junction to case, max	$^{\circ}\text{C}/\text{W}$	0.040	Direct current	Double side cooled
R_{thjc-A}			0.088		Anode side cooled
R_{thjc-K}			0.072		Cathode side cooled
R_{thck}	Thermal resistance, case to heatsink, max	$^{\circ}\text{C}/\text{W}$	0.008	Direct current	
MECHANICAL					
w	Weight, typ	g	180		
D_s	Surface creepage distance	mm (inch)	19.44 (0.765)		
D_a	Air strike distance	mm (inch)	12.10 (0.476)		

OVERALL DIMENSIONS



All dimensions in millimeters